ROADMAPS OF PACKAGING TECHNOLOGY

Chapter 1 An Introductory Perspective

Chapter 2 End User Roadmaps

Chapter 3 Metrics for Technology Performance

Chapter 4 Driving Forces on Packaging: The IC

Chapter 5 Driving Forces on Packaging: Physical Interconnects

Chapter 6 Chip Packaging: Thermal Requirements and Constraints

Chapter 7 Electrical Performance

Chapter 8 Evolutionary Advances in Conventional Packaging Technologies

Chapter 9 Chip Bonding at the First Level

Chapter 10 Grid Array Packaging: BGA and CSP

Chapter 11 Interconnect Substrate Technologies

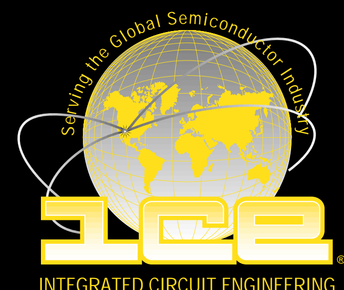
Chapter 12 Multichip Modules (MCMs)

Chapter 13 Next Generation Technologies

Table of Contents

Author
Eric Bogatin

Editors
Dick Potter
Laura Peters



ISBN: 1-877750-61-1

Graphic Artists

Jay Karcher

Alan Johnson

Becky Collins

Todd Wilson

Joe Czerwinski

Eric Shunk

© 1997 Integrated Circuit Engineering Corporation

The information on devices or arrangements contained in this text may be covered by patents. The disclosure of any information herein does not convey any license and no liability for patent infringement arising out of the information is assumed.

The information and data contained herein have been compiled from government and non-government technical reports and from material supplied by various manufacturers and are intended to be used for reference purposes. ICE does not warrant the accuracy of this information and data. The user is further cautioned that the data contained herein may not be used in lieu of other contractually cited references and specifications.

All rights reserved. No part of this publication may be reproduced in any form, or by any means without permission in writing from Integrated Circuit Engineering Corporation, 15022 N. 75th Street, Scottsdale, AZ 85260.